

เอกสารอ้างอิง

- [1] www.thaigov.go.th
- [2] Abtew, M., Selvaduray, G., 2000, "Lead-free solders in microelectronics," *Materials Science and Engineering R*, Vol.27, pp:95-141.
- [3] Tu, K.N., 2007, *Solder Joint Technology*, Springer Series in Materials Science.
- [4] Ma, X., Wang, F., Qian, Y., Yoshida, F., 2003, "Development of Cu-Sn intermetallic compound at Pb-free solder/Cu joint interface," *Journal of Material Letters*, Vol.57, pp:3361-3365.
- [5] Rizvi, M.J., Bailey, C., Chan, Y., Islam, M.N., Lu, H., 2007, "Effect of adding 0.3 wt% Ni into Sn 0.7wt% Cu solder Part II: Growth of intermetallic layer with Cu during wetting and aging," *Journal of Alloys and Compounds*, Vol.438, pp:122-128.
- [6] Zbrzezny, A.R., Saugovsky, P., Perovic, D.D., 2007, "Impact of board and component metallizations on microstructure and reliability of lead-free solder joints," *Microelectronics Reliability*, Vol.47, pp:2205-2214.
- [7] Limaye, P., Vandavelde, B., Labie, R., Vandepitte, D., Valinden, B., 2008, "Influence of intermetallic properties on reliability of lead-free flip-chip solder joints," *IEEE Transactions on Advanced Packaging*, Vol.31, pp:51-57.
- [8] Kim, K.S., Huh, S.H., Sukanuma, K., 2003, "Effect of intermetallic compounds on properties of Sn-Ag-Cu lead-free soldered joints," *Journal of Alloys and Compounds*, Vol.352, pp:226-236.
- [9] Yoon, J.W., Jung, S.B., 2003, "Investigation of interfacial reactions between Sn-5Bi solder and Cu substrate," *Journal of Alloys and Compounds*, Vol.359, pp:202-208.
- [10] Chew, K.H., Pang, J.H.L., 2005, "Impact of drop-in lead free solders on microelectronics packaging," *Electronics Packaging Technology Conference*, pp:451-454.
- [11] Amagai, M., Toyoda, Y., Ohnishi, T., Akita, S., 2004, "High drop test reliability: Lead-free solders," *Electronic Components and Technology Conference*, pp:1304-1309.
- [12] Bath, J., 2010, *Lead-Free Soldering*, Springer.
- [13] *Test Procedures for Developing Solder Data*, National Institute of Standards and Technology, USA.
- [14] Yu, D.Q., Wu, C.M.L., Law, C.M.T., Wang, L., Lai, J.K.L., 2005, "Intermetallic compounds growth between Sn-3.5Ag lead-free solder and Cu substrate by dipping method," *Journal of Alloys and Compounds*, Vol.392, pp:192-199.

- [15] Ma, X., Qian, Y., Yoshida, F., 2002, "Effect of La on the Cu-Sn intermetallic compound (IMC) growth and solder joint reliability," *Journal of Alloys and Compounds*, Vol.334, pp:224-227.
- [16] Ghosh, G., 2000, "Interfacial microstructure and the kinetics of interfacial reaction in diffusion couples between Sn-Pb solder and Cu/Ni/Pd metallization," *Acta Materialia*, Vol.48, pp:3719-3738.
- [17] Schaefer, M., Fournelle, R.A., Liang, J., 1998, "Theory for intermetallic phase growth between Cu and liquid Sn-Pb solder based on grain boundary diffusion control," *Journal of Electronic Materials*, Vol.27, pp:1167-1176.
- [18] Kim, H.K., Tu, K.N., 1996, "Kinetic analysis of the soldering reaction between eutectic SnPb alloy and Cu accompanied by ripening," *Physics Review B*, Vol.53, pp:16027-16034.
- [19] Mookam, N., Kanlayasiri, K., 2012, "Evolution of the intermetallic compounds found between Sn-0.3Ag-0.7Cu low-silver, lead-free solder and Cu substrate during thermal aging," *Journal of Materials Science and Technology*, Vol.28, pp:53-59.
- [20] Sun, P., Andersson, C., Wei, X., Cheng, Z., Shangguan, D., Liu, J., 2006, "High temperature aging study of intermetallic compound formation of Sn-3.5Ag and Sn-4.0Ag-0.5Cu solders on electroless Ni(P) metallization," *Journal of Alloys and Compounds*, Vol.425, pp:191-199.
- [21] Yoon, J.W., Kim, S.W., Jung, S.B., 2004, "Effect of reflow time on interfacial reaction and shear strength of Sn-0.7Cu solder/Cu and electroless Ni-P BGA joints," *Journal of Alloys and Compounds*, Vol.385, pp:192-198.
- [22] Mookam, N., Kanlayasiri, K., 2011, "Effect of soldering condition on formation of intermetallic phases developed between Sn-0.3Ag-0.7Cu low-silver lead-free solder and Cu substrate," *Journal of Alloys and Compounds*, Vol.509, pp:6276-6279.
- [23] Nagaoka, T., Morisada, Y., Fukusumi, M., Takemoto, T., 2011, "Selection of soldering temperature for ultrasonic-assisted soldering of 5056 aluminum alloy using Zn-Al system solders," *Journal of Materials Processing Technology*, Vol.211, pp:154-1539.
- [24] Lin, J.T., Bhattacharyya, D., Kecman, V., 2003, "Multiple regression and neural networks analyses in composites machining," *Composites Science and Technology*, Vol.63, pp:539-548.
- [25] Korkut, I., Acir, A., Boy, M., 2011, "Application of regression and artificial neural network analysis in modeling of tool-chip interface temperature in machining," *Expert Systems with Applications*, Vol.38, pp:11651-11656.
- [25] Lee, J., Um, K., 2000, "A comparison in back-bead prediction of gas metal arc welding using multiple regression analysis and artificial neural network," *Optics and Lasers in Engineering*, Vol.34, pp:149-158.

[27] Kanlayasiri, K., 2008, "Prediction of weld geometry using artificial neural networks and multiple regression technique," First Regional Conference in Manufacturing Engineering, November 24-25, 2008, Manila, Philippines.

[28] Ren, F., Case, E.D., Timm, E.J., and Schock, H.J., 2008, "Hardness as a function of composition for n-type LAST thermoelectric material," Journal of Alloys and Compounds, Vol.455, pp:340-345.